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**(54) EPOXY RESIN MOLDING MATERIAL FOR
SEALING AND ELECTRONIC PART DEVICE**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide an epoxy resin molding material which is used for sealing, can achieve flame retardance in a state free from a halogen and antimony, has good reliability for molding, reflow crack resistance, and so on, and has excellent storage stability, and to provide an electronic part device equipped with an element sealed with the same.

SOLUTION: This epoxy resin molding material for sealing, contains (A) a dihydrobenzooxadine

ring-having thermosetting resin, (B) an epoxy resin, (C) a phenolic resin, (D) a phosphate, and (E) an inorganic filler as essential components, wherein the melting point of the mixture of (A) the component, (B) the component and (C) the component is ≤ 2 P at 150°C, and wherein the content of (D) the component is 1 to 50 pts.wt. per 100 pts.wt. of the total amount of (A) the component, (B) the component and (C) the component, and the electronic part device equipped with an element sealed with the epoxy resin molding material for sealing.

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